July 2014



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current ,per IEC 61000-4-5	I _{PP_I/O}	4.7	Α	I/O to V _{SS} , 8/20µs
Operating Voltage (DC)	V_{DC}	6	V	V _{CC} to V _{SS}
ESD Protection – Contact Discharge	V _{ESD_I/O}	±16	kV	I/O to V _{SS} , per IEC 61000-4-2
	$V_{\text{ESD}}V_{\text{CC}}$	±30	kV	Vcc to V _{SS} , per IEC 61000-4-2
CCD Protection Air Discharge nor ICC 64000 4	$V_{\text{ESD_I/O}}$	±19	kV	I/O to V _{SS} , per IEC 61000-4-2
ESD Protection – Air Discharge, per IEC 61000-4-2	$V_{ESD}V_{CC}$	±30	kV	V _{CC} to V _{SS} , per IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P_{D}	380	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R\theta_{JA}$	327	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

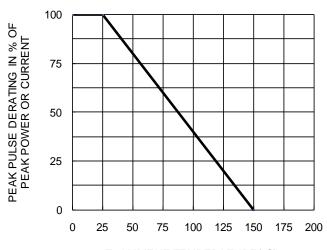
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	Vrwm	_	_	5.5	V	V _{CC} to V _{SS}
Reverse Current (Note 6)	I _{R(} V _{CC to} V _{SS)}	_	_	5.0	μΑ	V _R = 5V, V _{CC} to V _{SS}
Reverse Current (Note 6)	I _{R(IO to} V _{SS)}	_	_	1.0	μA	$V_R = 5V$, any I/O to V_{SS}
Reverse Breakdown Voltage	VBR	6.0	_	9.0	V	I _R = 1mA, V _{CC} to V _{SS}
Forward Clamping Voltage	V_{F}	_	0.8	1.0	V	$I_F = 15mA$, V_{SS} to V_{CC}
Reverse Clamping Voltage (Note 7)	$V_{C_{-}I/O}$	_	8.5	_	V	$I_{PP} = 4.7A$, I/O to V_{SS} , 8/20 μ s
ESD Clamping Voltage	Vesd_Vcc	_	10	_	V	TLP, 20A, tp = 100 ns, V_{CC} to V_{SS}
	Vesd_I/O	_	12	_	V	TLP, 20A, tp = 100 ns, I/O to V_{SS}
Dynamic Resistance	$R_{DIF}V_{CC}$	_	0.2	_	Ω	TLP, 20A, tp = 100 ns, V_{CC} to V_{SS}
	R _{DIF_I/O}	_	0.3	_	Ω	TLP, 20A, tp = 100 ns, I/O to V _{SS}
Channel Input Capacitance	$C_{I/O \ to} \ V_{SS}$	_	0.55	0.65	pF	$V_R = 2.5V, V_{CC} = 5V, f = 1MHz$
Channel Input Capacitance	C _{I/O to} V _{SS}		0.65	_	pF	V _R = 2.5V, V _{CC} = floating, f = 1MHz
Variation of Channel Input Capacitance	CI/OMAX-CI/OMIN	_	0.03	_	pF	V _{CC} = 5V, V _{SS} = 0V, I/O = 2.5V, f =1MHz, T=25 °C, C _{I/OMAX} -C _{I/OMIN}
Variation of Channel Input Capacitance	CI/OMAX-CI/OMIN	_	0.05	_	pF	V_{CC} = floating , V_{SS} = 0V, I/O = 2.5V, f =1MHz, T = +25°C , $C_{I/OMAX}$ - $C_{I/OMIN}$

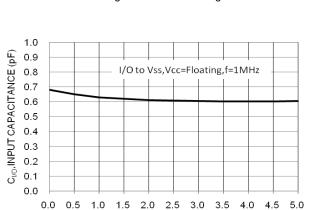
Notes:

- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an $8x20\mu s$ peak pulse current (I_{pp}) waveform.

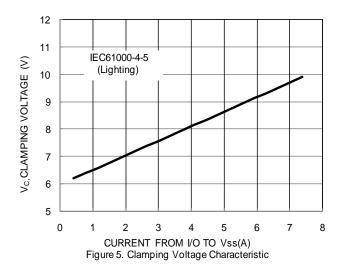


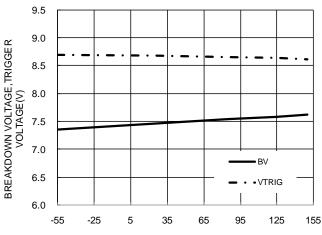


T_A,AMBIENT TEMPERATURE(°C) Figure1. Pulse Derating Curve

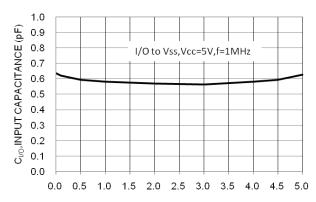


V_{I/0,} INPUT VOLTAGE (V) Figure 3. Input Capacitance vs. Input Voltage





T_A, AMBIENT TEMPERATURE (°C) Figure 2. BV, Trigger Voltage vs. Ambient Temperature



V_{I/O,} INPUT VOLTAGE (V) Figure 4. Input Capacitance ∨s. Input Voltage

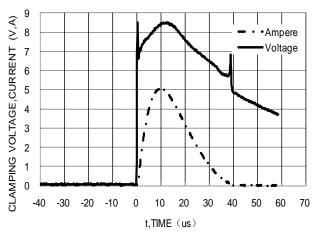


Figure 6. Waveform of Clamping Voltage, Current vs. Time(8/20us, I/O to Vss)



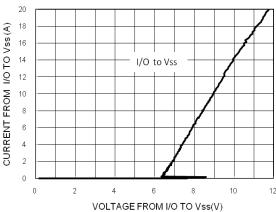
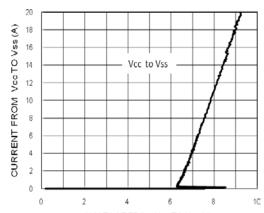


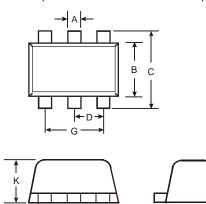
Figure 7. Transmission Line Pulsing (TLP) Measurement
Current vs. Voltage



VOLTAGE FROM Vcc TO Vss(V)
Figure 8. Transmission Line Pulsing (TLP) Measurement
Current vs. Voltage

Package Outline Dimensions

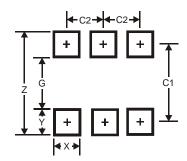
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT563				
Dim	Min	Max	Тур	
Α	0.15	0.30	0.20	
В	1.10	1.25	1.20	
С	1.55	1.70	1.60	
D	-	-	0.50	
G	0.90	1.10	1.00	
Н	1.50	1.70	1.60	
K	0.55	0.60	0.60	
L	0.10	0.30	0.20	
M	0.10	0.18	0.11	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Υ	0.5
C1	1.7
C2	0.5



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